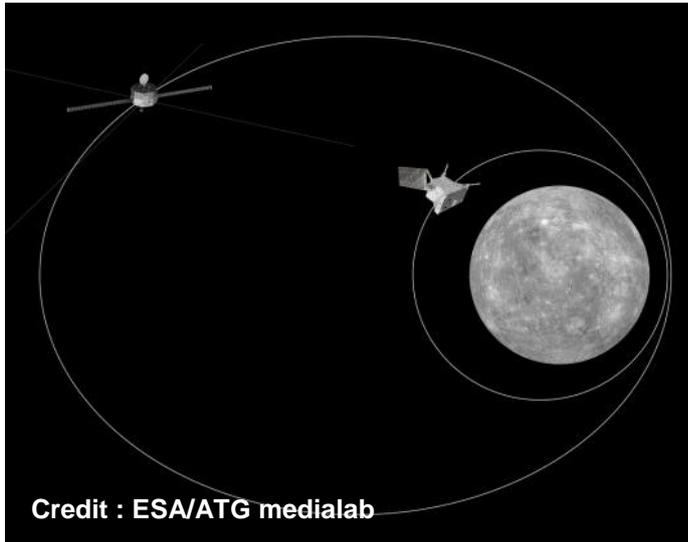


On October 20th, BepiColombo, the joint mission of the Japanese and the European space agencies (JAXA and ESA), has been successfully launched from Kourou, French Guiana.



Buc, France, October 23rd 2018 – BepiColombo is the Europe's first mission to Mercury, the closest planet to the sun and the least explored terrestrial planet in the inner Solar System. Because of the planet's proximity to the Sun and its harsh environment, the mission has been identified as one of the most challenging long-term planetary projects.

The mission consist in sending two probes that will orbit the planet and provide a comprehensive view of Mercury. The Mercury Planetary Orbiter (MPO) probe has been developed by ESA while the Institute of Space and Astronautical Science (ISAS) at JAXA,

has developed the second probe, the Mercury Magnetospheric Orbiter (MMO or Mio). The two probes should reach orbit late in 2025 and MPO will map Mercury's entire surface and study its structure and composition while Mio will analyze its magnetic field.

3D PLUS supplied several electronic parts for BepiColombo mission. Integrated in the computer boards, our SRAM and EEPROM provide the highest density while smallest footprint with more than 85% space savings in the design, high reliability and radiation tolerance. Used as high-density storage memory in Data Recorder, 3D PLUS SDRAM offers a space quality level and a very large flight heritage worldwide, with a technology proven for 15 to 18 years missions in space. 3D PLUS supplied Point-of-loads Converters and developed a custom low noise amplifier integrated in the Mercury Magnetospheric Orbiter (Mio).

Benefitting from its strong flight heritage, 3D PLUS modules have already traveled until the Moon, Mars, the Tchouri comet, Jupiter and they are today traveling to reach Mercury in the next years. 3D PLUS is very proud to contribute to such challenging missions with such ambitious scientific objectives, as they will allow a better knowledge of the Solar System and understand planets' history and composition, including Earth.

About 3D PLUS:

3D PLUS is a French SME, world leader in the design and manufacturing of high-performance and high reliability components miniaturized with its unique 3D vertical interconnect technology.

With more than 125,000 modules into space early 2018 and a production of more than 30,000 space qualified modules per year in its facility nearby Paris, 3D PLUS provides all stakeholders of the global space industry for over 20 years for telecommunications applications, Earth observation, navigation, launchers and human spaceflight, science missions, small satellites and constellations.